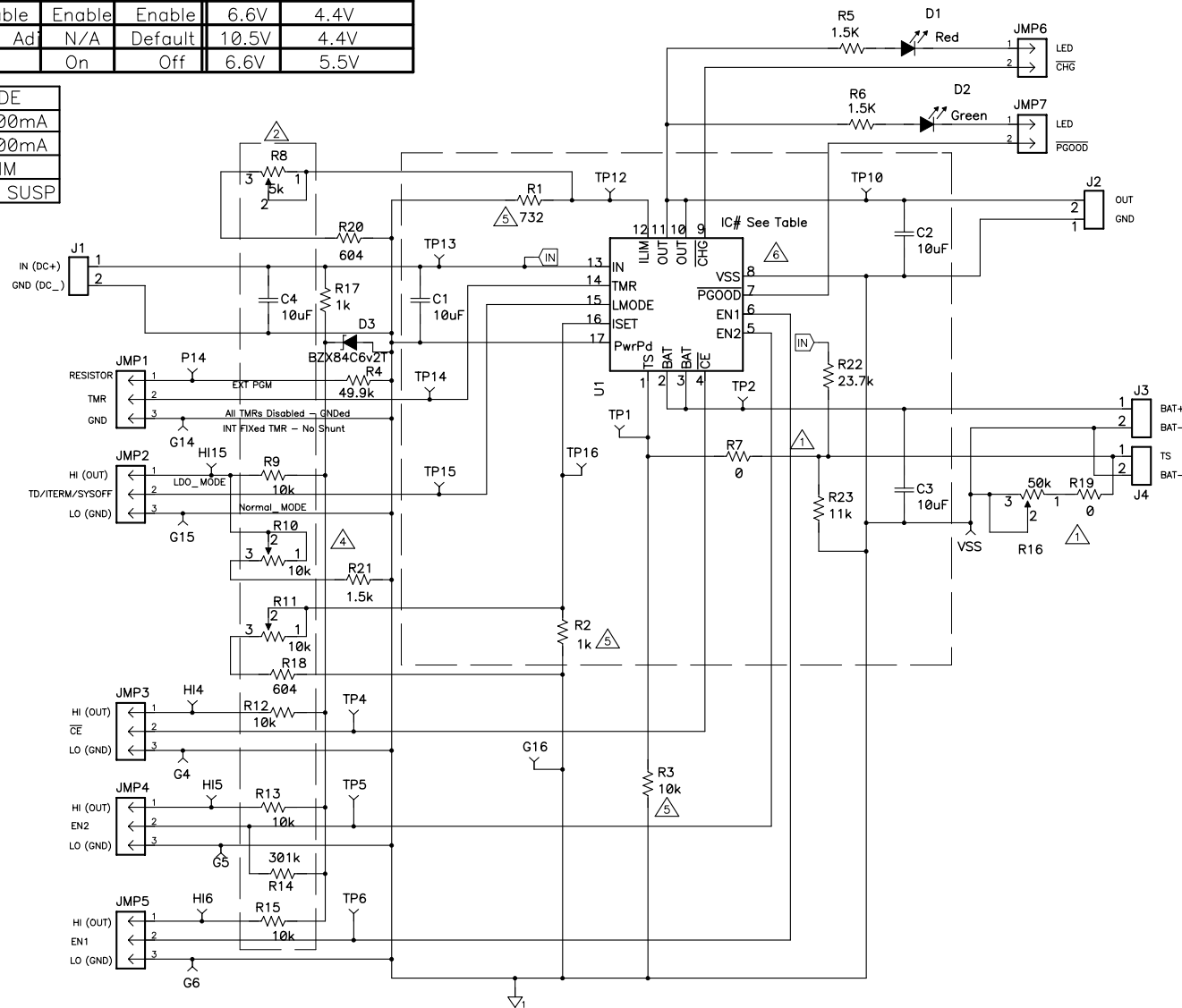


For all ICs Pin 15 is the unique pin. The '7x are for higher current and '23x for lower current.
 bq24072/3/4/5/9(T) = '72 or '73 or '74 or '75 or '79 or '79T
 bq24230/2 = '230 or '232

Jumper	JMP - 2				
Signal U1-15_IC	HI	LOW	FLOAT	OVP	VOUT
TD '72	Disable	Enable	Enable	6.6V	VBAT+200mV
TD '73, '230	Disable	Enable	Enable	6.6V	4.4V
ITERM '74, '232	POT Ad	N/A	Default	10.5V	4.4V
SYSOFF '75, '79(T)	Off	On	Off	6.6V	5.5V

EN2	EN1	MODE
0	0	100mA
0	1	500mA
1	0	ILIM
1	1	CE SUSP



- ⚠ There are two types of TS control 1) Voltage based - R7, R22 and R23 installed (R3 not installed) & 2) Current based - No resistors required (R3, R7, R22, R23, R19 and R16, but apply short to R7) or an optional adjustment using R3 and R7. A "thermistor" is required either externally or on the PCB: R19 and R16 can be used in place of the thermistor for either TS type or R3 can replace all the resistors for the current based.
- ⚠ Resistors, in dotted box, typically not needed in a design but used here to assist in evaluation of the IC or to protect the EVM from incorrect input connections (R8 through R14). C4 may be used, if needed, for higher current applications.
- ⚠ Resistors, in the dashed box are the required components for a simplified design. Components outside the dashed box are optional components. See data sheet for more detail on desired features.
- ⚠ R10 is used for the ITERM feature found only on bq24078(T)
- ⚠ Not used See BOM for different Configurations.
- ⚠ Refer to Data sheet to if a "T" version of the the IC is available. The "T" (bq24072T) implies that the TS pin is voltage based instead of current based.

Texas Instruments

Title			bq24072/3/4/5/9(T)		
Size	Number	Rev			
C	HPA282 / HPA502	B			
Date	Tue Jul 14, 2009	Drawn by	CHM		
Filename	HPA282B_UG.sch	Sheet	1	of	1

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